

Bio and nano packaging techniques for electron devices : advances in electronic device packaging

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Abstrak

This book discusses future trends and developments in electron device packaging and the opportunities of nano and bio techniques as future solutions. It offers a comprehensive overview of nano particles and nano composites and their application as packaging functions in electron devices. The importance and challenges of three-dimensional design and computer modeling in nano packaging is discussed, also ways for implementation are described. Solutions for unconventional packaging solutions for metallizations and functionalized surfaces as well as new packaging technologies with high potential for industrial applications are discussed. The book brings together a comprehensive overview of nano scale components and systems comprising electronic, mechanical and optical structures.